

AMENDMENTS TO THE SPECIFICATION:

Please delete the original Abstract as set forth on page 36 of Applicants' disclosure as originally filed, in its entirety, and substitute therefor the following new Abstract:

-- ABSTRACT OF THE DISCLOSURE

A method of manufacturing an electronic device comprising IC elements~~40~~, on a set of opposite faces of which a first electrode~~12~~ and a second electrode~~13~~ are formed, a first circuit layer~~20~~ where an antenna circuit~~24~~ having a slit~~4~~ is formed, and a second circuit layer~~30~~ for electrically connecting the IC elements~~10~~ and the antenna circuit~~24~~. The IC elements~~10~~ are placed individually in cutouts~~74~~, into each of which one IC element~~10~~ can be inserted, the cutouts being formed in the outer circumference of a disk-like carrier~~70~~. Thus, with the method, an electronic device that is inexpensive and is manufactured with high productivity, and has improved communication characteristics, is manufactured. --